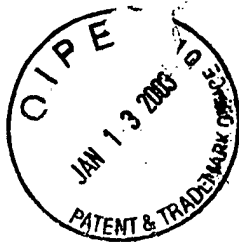


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By: Lothar Bauch

Date: Jan 6, 2003

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Lothar Bauch et al.

Applic. No. : 10/082,554

BEST AVAILABLE COPY

Filed : February 25, 2002

Title : Stacked VIA with Specially Designed Landing Pad for Integrated Semiconductor Structures

Examiner : Pershelle L. Greene

Group Art Unit : 2826

A M E N D M E N T

Hon. Commissioner of Patents and Trademarks,
Washington, D. C. 20231

S i r :

Responsive to the non-final Office action dated September 6, 2002, kindly amend the above-identified application as follows:

In the Claims:

Cancel claims 8 and 9.